

Abstract

An adhesive sheet composed of a blend of a synthetic rubber S1 and a thermoplastic 2,

- a) the blend being microphase-separated,
- 5 b) the blend possessing at least two softening temperatures, at least one softening temperature being greater than 65°C and less than 125°C,
- c) a G' at 23°C, as measured by test method A, of greater than 10^7 Pas,
- d) a G'' at 23°C, as measured by test method A, of greater than 10^6 Pas,
- e) and a crossover, as measured by test method A, of less than 125°C
- 10 for bonding electrical modules in chip cards.